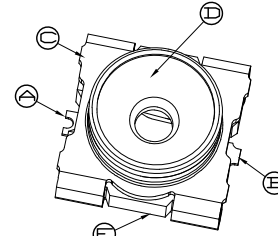
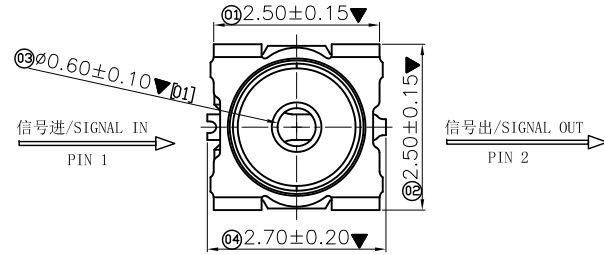
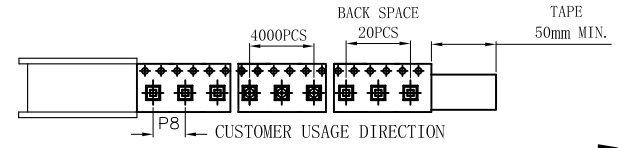
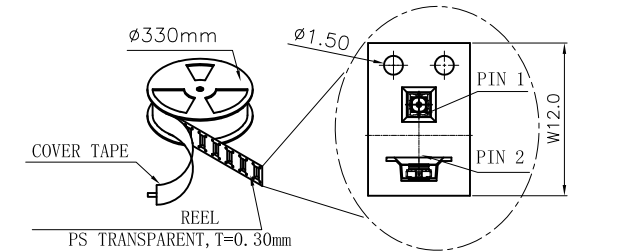


REV.	ECN NUMBER	DESCRIPTION	DATE	DRAWN	CHECKD	APPROVED
A	ECN211723	FIRST RELEASE	05/16'22	Qian	Martin	Ken
B	ECN246612	修改包规数量	11/06'24	SAM	Martin	Ken



3D VIEW

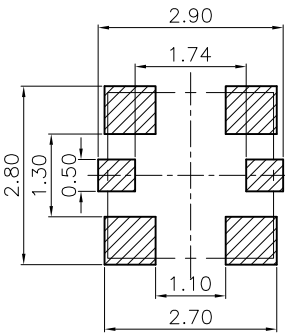


备注/NOTES:

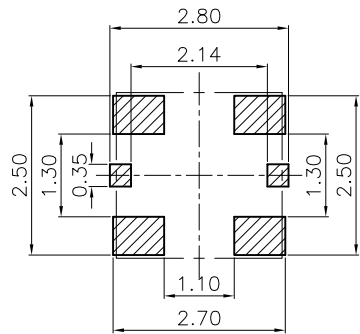
- 额定功率/POWER RATING: 2W
- 频率范围/FREQUENCY RANGE: DC~11GHz
- 特性阻抗/IMPEDANCE: 50 Ω
- 工作温度/OPERATING TEMPERATURE: -40℃~+85℃
- 绝缘电阻/INSULATION RESISTANCE: 500M Ω MIN.
- 耐电压/WITHSTANDING VOLTAGE: 300V AC & 1 MINUTE
- 初始接触电阻/INITIAL CONTACT RESISTANCE: 120m Ω MAX. (减板电阻/WITHOUT CONDUCTOR RESISTANCE)
- 驻波比/VOLTAGE STANDING WAVE RATIO (VSWR):
 - 1.2 MAX. (DC~3GHz)
 - 1.3 MAX. (3~6GHz)
 - 1.5 MAX. (6~11GHz)
- 插损/INSERTION LOSS:
 - 0.10dB MAX. (DC~3GHz)
 - 0.20dB MAX. (3~6GHz)
 - 0.60dB MAX. (6~11GHz)
- 隔离度/ISOLATION:
 - 20 dB MIN. (DC~3GHz)
 - 15 dB MIN. (3~6GHz)
 - 10 dB MIN. (6~11GHz)
- 耐久性/DURABILITY: 500 CYCLES.
- 载带与卷盘包装/PACKING TAPE & REEL: 4000PCS/REEL (Φ330mm)
- 回流焊次数/IR REFLOW CYCLE: 2CYCLES.

⑧	下胶芯/DOWN HOUSING	1	LCP UL94V-0/BLACK
⑨	上胶芯/TOP HOUSING	1	LCP UL94V-0/BLACK
⑩	外壳/SHELL (地/GND)	1	COPPER ALLOY/Ni:50u" MIN, Au:1u" MIN;
⑪	PIN 2(OUTPUT)	1	SUS/Ni:50u"MIN, CONTACT AREA Au:5u"MIN, SOLDER AREA Au:1u" MIN
⑫	PIN 1(INPUT)	1	SUS/Ni:50u"MIN, CONTACT AREA Au:5u"MIN, SOLDER AREA Au:1u" MIN
项目/ITEM	描述/DESCRIPTION	数量/Q'TY	材料(MATERIAL)/完成(FINISH)

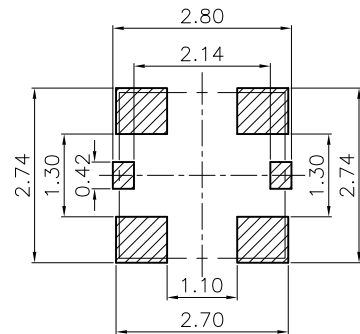
BOM清单/BOM LIST



推荐的PCB布局/RECOMED PCB LAYOUT
一般公差/GENERAL TOLERANCE: ±0.05



推荐钢网/RECOMMEND METAL MASK
(钢网厚度/MASK THICKNESS 0.12mm)



推荐钢网/RECOMMEND METAL MASK
(钢网厚度/MASK THICKNESS 0.10mm)

	GENERAL TOLERANCE		SCALE: 1:1	DRAWN SAM	DATE 11/06'24	DWG. NO. 600-24668-01	TITLE CUSTOMER DRAWING MINI RF 2GEN CONN., L2.5*W2.5*H1.5mm	REV. B
	XX. ±0.50							
	X. ±0.35	X° ±2.0°	UNIT: mm	CHECK	DATE	PARTS NO.(INTENDED USE) 818024668		SHEET 1/1
	.X ±0.25	.X° ±1.0°						
	.XX ±0.15	.XX° ±0.5°	SIZE: A4	APPROVE	DATE			